**ENGINEERING** 

## PRODUCT SPECIFICATION

DEPT. For CJ02 Series Board Mound Telephone Jack

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SPEC.NO.: SPCJ005D

1. SCOPE:

This specification contains the test requirement of subject connectors when tested under the condition and below standards base on CviLux test procedure

2. APPLICABLE STANDARDS:

MIL - STD - 202 Methods for test of connectors for electronic equipment

MIL - STD - 1344 Test methods for electrical connectors

3. APPLICABLE SERIES NO.: CJ02 Series

4. SHAPE, CONSTRUCTION AND DIMENSIONS

See attached drawings

5. MATERIALS

See attached drawings

6. ACCOMMODATED P.C.BOARD

6.1 Thickness: 1.6 mm (.063")

6.2 P.C. Board Layout: See attached drawings



REVIEWED: <u>Alex</u> APPROVED: <u>David</u> VERIFIED: <u>Sandy</u>.



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## 7. ELECTRICAL PERFORMANCE:

	ITEM	TEST CONDITION	REQUIREMENT
7.1	Rated current and voltage		1.5A 125V AC (r.m.s.)
7.2	Contact resistance	Dry circuit of DC 20 mV max. 100 mA max.	Less than $20 \text{ m}\Omega$
7.3	Dielectric strength	When applied AC 1000 V 1 minute between adjacent terminal	No change
7.4	Insulation resistance	When applied DC 500 V between adjacent terminal or ground	More than 500 M $\Omega$

## 8. MECHANICAL PERFORMANCE:

	ITEM	TEST CONDITION	REQUIREMENT
8.1	Mating force	Measure force to mate samples at speed 25±3mm per minute with plug latch depressed	2.27 Kgf (5 lb) max.
8.2	Retention force (Between the jack and plug)	Retention speed 25±3mm per minute from jack	7.7 Kgf (17 lb) min.
8.3	Durability	Connector shall be subjected to 300 cycles of insertion and withdrawal	Contact resistance: Less than twice of initial

## 9. ENVIRONMENTAL PERFORMANCE:

	ITEM	TEST CONDITION	REQUIREMENT
9.1	Vibration	1.5 mm 10 - 55 - 10 HZ/minute each 2 hours for X,Y and Z directions	Appearance: No damage Discontinuity: 1 micro second max.
9.2	Solder ability	Soldering time: 5±0.5 second Soldering pot: 230± 5°C	Minimum: 90% of immersed area
9.3	Resistance to soldering heat	Soldering time: 5±0.5 second Soldering pot: 260±5°C	No damage
9.4	Heat aging	105±2°C, 96 hours	No damage
9.5	Humidity	40±2°C, 90-95% RH, 96 hours measurement must be taken within 30 min. after tested	Appearance: No damage Contact resistance: Less than twice of initial Dielectric strength: To pass para 7-3



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	ITEM	TEST CONDITION	REQUIREMENT
9.6	Temperature cycling	One cycle consists of:  (1) -55 +0 °C, 30 min.  (2)Room temp. 10-15 min.  (3) 85 +3 °C, 30 min.  (4)Room temp. 10-15 min.	Appearance: No damage Contact resistance: Less than twice of initial
9.7	Salt spray	Temperature: 35±3°C Solution: 5±1% Spray time: 48±4 hours Measurement must be taken after water rinse	Appearance: No damage Contact resistance: Less than twice of initial

10. AMBIENT TEMPERATURE RANGE: -40 to + 105°C